Product/Process Change Notification

N° 2020-024-A

Dear customer,

please find attached our Infineon Technologies AG PCN:

Several changes affecting product family HIG-GBD1 and FS200R07A02E3_S6

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2022-01-02.
- Infineon aligns with the widely-recognized JEDEC STANDARD “JESD46“, which stipulates:
  “Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”

  Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

On 16 April 2020, Infineon acquired Cypress.
We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.
For further details, please visit our website:
https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/

Infineon Technologies AG
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Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Constanze Hufenbecher, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

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Products affected	Please refer to attached affected product list 1_cip20024_A

Detailed change information

Subject:	Several changes affecting product family HIG-GBD1 and FS200R07A02E3_S6
Reason/Motivation:	According to the global Infineon production strategy, the wafer production and the wafer test of the affected products will be transferred to Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia, and the assembly production, and final test will be transferred to Infineon Technologies (Wuxi) Co. Ltd., Wuxi, China. This ensures secure and increased capacity for running and future products.

Description	**Old**	**New**
PROCESS - WAFER PRODUCTION: New / change of metallization (specifically chip frontside)	**IGBT3 only**, Frontside metallization thickness 3.2 µm	**IGBT3 only**, Frontside metallization thickness 5.0 µm
PROCESS - WAFER PRODUCTION: Move all or parts of production to a different wafer fab site	**Wafer fabrication, preassembly** Infineon Technologies Austria AG, Villach, Austria	**Wafer fabrication, preassembly** Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia
PROCESS - ASSEMBLY: Change of specified assembly process sequence	Preform soldering	Paste soldering
PROCESS - ASSEMBLY: Move all or parts of production to a different assembly site	**Entire assembly production** Infineon Technologies AG, Regensburg, Germany and Infineon Technologies AG, Warstein, Germany	**Assembly production** Infineon Technologies (Wuxi) Co. Ltd., Wuxi, China **Plating only** Welnew Micro-Electronics Co. Ltd., Shanghai, China

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TEST FLOW: Move of all or part of electrical wafer test and/or final test to a different test site	**Wafer Test** Infineon Technologies Austria AG, Villach, Austria **Final Test** Infineon Technologies AG, Regensburg, Germany	**Wafer Test** Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia **Final Test** Infineon Technologies (Wuxi) Co. Ltd., Wuxi, China
Change of labelling/SP number	HIG-GBD1: SP001661214 FS200R07A02E3_S6: SP001661220	HIG-GBD1: SP005577255 FS200R07A02E3_S6: SP005577662

Product identification

Traceability assured via lot number and different SP number.

Anticipated impact of change

No impact on electrical performance. Quality and reliability verified by qualification. There is no change in form, fit, and function.

DeQuMa-ID(s): SEM-PW-07 / SEM-PW-13 / SEM-PA-17 / SEM-PA-18 / SEM-TF-01 / SEM-PS-04

Attachments

1_cip20024_A	affected product list
3_cip20024_A	customer information package

Time schedule

Final qualification report	available, see 3_cip20024_A
First samples available	2021-09-30
Intended start of delivery [1]	2022-04-01
Last order date (LOD) [2]	2022-05-31
Last delivery date (LDD) [3]	2022-09-30

If you have any questions, please do not hesitate to contact your local sales office.

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Sales name	SP number	OPN	Package
FS200R07A02E3_S6	SP001661220	FS200R07A02E3S6BKSA2	PG-MDIP-28-1
FS200R07A02E3_S6	SP005577662	FS200R07A02E3S6BKSA3	PG-MDIP-28-1
HIG-GBD1	SP001661214	HIGGBD1BKSA2	PG-MDIP-28-1
HIG-GBD1	SP005577255	HIGGBD1BKSA3	PG-MDIP-28-1